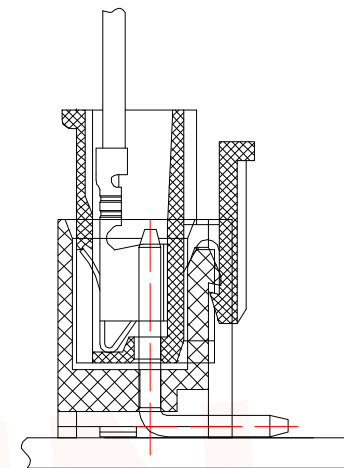
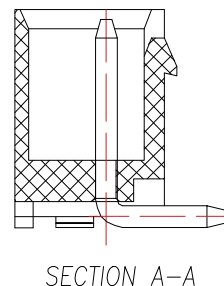
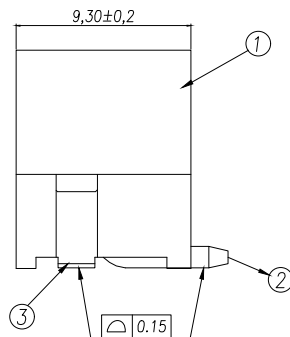
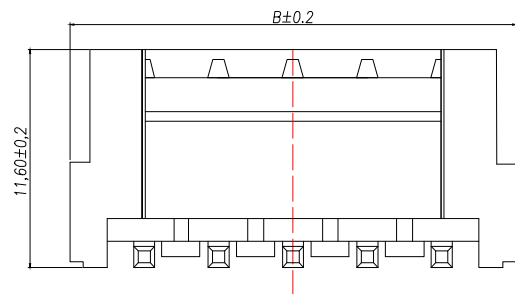
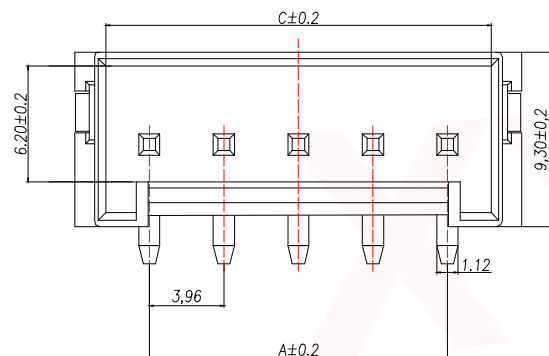
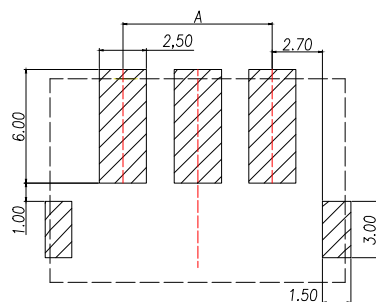




SUGGESTED PCB LAYOUT
(COMPONENT SIDE)



Part No	Pin	A	B	C
XY-VH3.96-2A51	2	3.96	11.88	8.60
XY-VH3.96-3A51	3	7.92	15.84	12.56
XY-VH3.96-4A51	4	11.88	19.80	16.52
XY-VH3.96-5A51	5	15.84	23.76	20.48
XY-VH3.96-6A51	6	19.80	27.72	24.44
XY-VH3.96-7A51	7	23.76	31.68	28.40
XY-VH3.96-8A51	8	27.72	35.64	32.36
XY-VH3.96-9A51	9	31.68	39.60	36.32
XY-VH3.96-10A51	10	35.64	43.56	40.28



SUGGESTED PCB LAYOUT
(COMPONENT SIDE)

技术要求:

1. 塑料材料: LCP(UL-94V-0)
2. 接触件: 黄铜镀锡
3. 接触电阻: $\leq 30\text{m}\Omega$
4. 绝缘电阻: $\geq 1000\text{M}\Omega$
5. 额定电压: 250V AC DC
6. 额定电流: 7.0A AC DC
7. 耐压: 能承受 1000V AC/Minute
8. 工作温度: $-25^{\circ}\sim+85^{\circ}$
9. 可焊性试验: 浸锡面积 $\geq 95\%$ 温度 260, 时间 $2.5\pm 0.5\text{s}$
10. 铅和铜等六大有害物质含量要符合环保要求。

3	焊片 Fitting Nail	黄铜	2	电镀(锡): 整个表面镀底镍 30u"MIN, 再镀锡80u"MIN
2	端子 Contact	黄铜	N*1	电镀(锡): 整个表面镀底镍 30u"MIN, 再镀锡80u"MIN
1	基座 Wafer	LCP (UL94V-0)	1	米色
序号	名称	材料	数量	备注

DIMENSION IN mm		厦门市辛译精密电子有限公司 Xiamen XinYi Xyeconn Electronics Co.,Ltd			
TOLERANCE UNLESS OTHERWISE SPECIFIED					
.X±0.35	X.*± 5°	APR. Alex	TITLE: 3.96MM 立贴		
.XX±0.25	.X*± 3°	CHK. Jack	DWG NO. XY-VH3.96-NA51		
.XXX±0.15	.XX*± 1°	DRA. Can	PROJ.		CUSTOMER DRAWING
			SIZE A4	SCALE 1:1	SHEET 1/1 REV. A